

LAPIS Semiconductor ML9270-xx

33-Segment VFD Driver

GENERAL DESCRIPTION

The ML9270-xx is a monolithic IC designed for directly driving the anode of the vacuum fluorescent display tube. The device contains a 34-bit shift register circuit, 33-bit latch circuit, PLA (33*33 Matrix) and 33-output circuit on a single chip.

Display data is serially stored in the shift register at the rising edge of a CLOCK pulse.

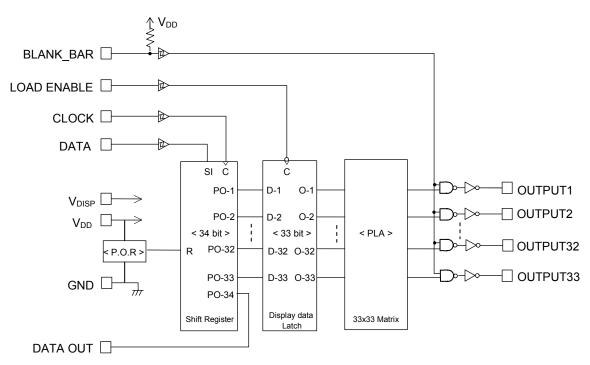
Setting the BLANK_BAR pin low allows all the driver outputs to be driven low, which makes it possible to set the display blanking.

: 44-pin plastic QFP (QFP44-P-910-0.80-2K)

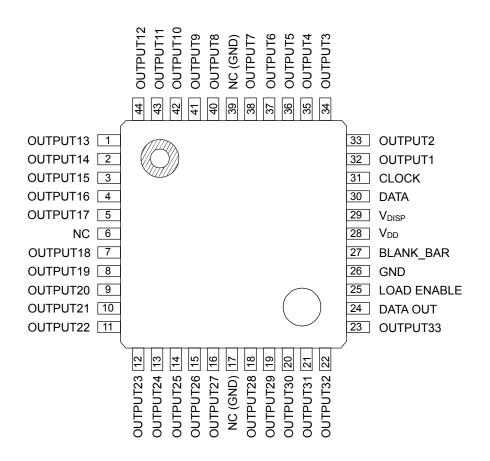
FEATURES

- Logic power supply (V_{DD}) : 3.3 V±10% or 5.0 V±10%
- VFD tube drive power supply (V_{DISP}) : 8 to 18 V
- VFD driver output can be connected directly to the VFD tube. No pull-down resistor is required.
- VFD driver output current
 - Segment driver (OUTPUT1 to 13) $:-6.0 \text{ mA} (V_{\text{DISP}} = 9.5 \text{V})$
 - Segment driver (OUTPUT14 to 21) : $-1.5 \text{ mA} (V_{\text{DISP}} = 9.5 \text{V})$
- Segment driver (OUTPUT22 to 33) : $-6.0 \text{ mA} (V_{\text{DISP}} = 9.5 \text{V})$
- Data transfer speed : 5.0MHz
- Package
- Built-in power on reset circuit

BLOCK DIAGRAM



PIN CONFIGURATION (TOP VIEW)



2/13

PIN DESCRIPTION

Pin	Symbol	Туре	Connects to	Description	
32 to 38, 40 to 44, 1	OUTPUT 1 to 13	0	VFD tube anode	High voltage driver outputs for driving VFD tube. The driver outputs are in phase with the corresponding latch outputs.	
11 to 16, 18 to 23	OUTPUT 22 to 33	U	electrode	The direct connection to the anode of a VFD tube eliminates pull-down resistors. $I_{OH1} > -1.5$ mA	
2 to 5, 7 to 10	OUTPUT 14 to 21	ο	VFD tube grid electrode	High voltage driver outputs for driving VFD tube. The driver outputs are in phase with the corresponding latch outputs. The direct connection to the anode of a VFD tube eliminates pull-down resistors. $I_{OH1} > -6.0$ mA	
24	DATA OUT	0	Next Device	Serial data output pin of shift register. Data in output through the DATA OUT pin in synchronization with the CLOCK signal.	
28	V _{DD}			Damas	V _{DD} -GND are power supplies for internal logic.
29	V _{DISP}	—	Power supply	$V_{\text{DISP}}\text{-}\text{GND}$ are power supplies for driving fluorescent tubes.	
26	GND			Apply V_{DISP} after V_{DD} is applied.	
25	LOAD ENABLE	I	Micro- Controller	Latch signal input pin of display data latch logic. If the LOAD ENABLE pin is high, the data of the shift register is through. If the LOAD ENABLE pin is low, the data of the shift register does the latch.	
27	BLANK_BAR	I	Micro- Controller	BLANK_BAR input pin with a built-in pull-up resistor. The BLANK_BAR pin is normally being set high. If the BLANK_BAR pin is low, the all driver outputs are "L" level.	
30	DATA	I	Micro- Controller	Serial data input pin of the shift register. Display data (positive logic) is input in through the DATA pin synchronization with CLOCK.	
31	CLOCK	I	Micro- Controller	Shift register clock input pin. Shift register reads data through DATA while the CLOCK pin is low state and the data in the shift register is shifted from one stage to the next stage at the rising edge of the CLOCK.	

Parameter Symbol Condition Rating Unit –0.3 to +6.5 Supply Voltage (1) V V_{DD} — Supply Voltage (2) VDISP –0.3 to +25 V ___ Input Voltage V_{IN} –0.3 to $V_{\text{DD}}\text{+}0.3$ V ____ Output Voltage (1) V_{01} DATA OUT -0.3 to V_{DD}+0.3 V V Output Voltage (2) V_{O2} OUTPUT1 to 33 -0.3 to V_{DISP}+0.3 °C Storage Temperature -55 to +150 T_{STG} Ta < 105°C **Power Dissipation** P_D 266 mW OUTPUT1 to 13, -18.0 to +2.0 I_{O1} OUTPUT 22 to 33 **Output Current** mΑ OUTPUT 14 to 21 -4.5 to +2.0 I_{O2} I_{O3} DATA OUT -2.0 to +2.0

ABSOLUTE MAXIMUM RATINGS

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Supply Voltage (1)	V	When the power supply voltage is 5.0 V (typ.)	4.5	5.0	5.5	V
Supply Voltage (1)	V _{DD}	When the power supply voltage is 3.3 V (typ.)	3.0	3.3	3.6	V
Supply Voltage (2)	V _{DISP}	_	8	_	18	V
CLOCK Frequency	f _{CLK}	—	_	_	5.0	MHz
Operating Temperature	Та	_	-40		+105	°C

ELECTRICAL CHARACTERISTICS

DC Characteristics

(V _{DD} = 5.0 V±10% or 3.3 V± Parameter	Symbol		Condition	Min.	Тур.	Max.	Unit
High Lovel Input Veltage	V	Allinguto	V_{DD} = 5.0 V \pm 10 %	0.7 V _{DD}	_	_	V
High Level Input Voltage	VIH	All inputs	V_{DD} = 3.3 V \pm 10 %	0.8 V _{DD}	_	—	V
Low Level Input Voltage	VIL	All inputs	V_{DD} = 5.0 V \pm 10 %	—	_	$0.3 V_{\text{DD}}$	V
Low Level input voltage	VIL	All inputs	V_{DD} = 3.3 V \pm 10 %	—		$0.2 V_{\text{DD}}$	V
High Level Input Current	I _{IH1}	*1	$V_{IH} = V_{DD}$	-1.0	—	+1.0	μA
riigii Level input Guiteint	I _{IH2}	BLANK_BAR	$V_{IH} = V_{DD}$	-1.0	—	+1.0	μA
	I _{IL1}	*1	$V_{IL} = 0.0 V$	-1.0	_	+1.0	μA
			V _{DD} = 5.0 V,	-120	-75	-30	μA
Low Level Input Current	I _{IL2}	BLANK_BAR	V _{IL} = 0.0 V	-120	-75	-30	μΑ
	IL2	*4	V _{DD} = 3.3 V,	-60	-38	-15	μA
			V _{IL} = 0.0 V	-00	-30	-15	μΛ
	V _{OH1}	*2	V _{DISP} = 9.5 V,	V _{DISP} -0.5	l		v
	VOHI	2	I _{OH1} = –6.0 mA	V DISP-0.0			v
	V _{OH2}	*3	V _{DISP} = 9.5 V,	V _{DISP} –0.5	_		v
High Level Output	V OH2	5	I _{OH2} = –1.5 mA	V DISP-0.0			v
Voltage			V_{DD} = 5.0 V,	V _{DD} -0.4	_		v
	V _{OH3}	DATA OUT	I _{OH3} = –500 uA	VDD-0. 4			v
	V OH3		V _{DD} = 3.3 V,	V _{DD} -0.3	_		v
			I _{OH3} = –500 uA	vDD-0.3			v
	V _{OL1}	*2, *3	V _{DISP} = 9.5 V,			2.0	v
	V OL1		I _{OL1} = 500 uA			2.0	v
Low Level Output			V_{DD} = 5.0 V,			0.4	v
Voltage	V _{OL2}	DATA OUT	I _{OL2} = 500 uA			0.4	v
	V OL2	DATA OUT	V _{DD} = 3.3 V,			0.3	v
			I _{OL2} = 500 uA			0.5	v
			V_{DD} = 5.0 V \pm 10 %			2.5	mA
Cumply Cumpat (1)	laa	V _{DD}	Input Data = "1"0"1"	_	—	2.5	IIIA
Supply Current (1) (Dynamic Mode)	I _{DD}	V DD	V_{DD} = 3.3 V \pm 10 %			2.0	mA
			Input Data = "1"0"1"	_	_	2.0	IIIA
	I _{DISP}	V _{DISP}	Input Data = "1"0"1"			0.5	mA
Supply Current (2)	I _{DDS}	V _{DD}	No Operation,	—	1.0	10.0	μA
(Static Mode)	IDISPS	V _{DISP}	Typ.: Ta = 25°C, Max.:Ta = 85°C		1.0	20.0	μA

 $(V_{DD} = 5.0 \text{ V} \pm 10\% \text{ or } 3.3 \text{ V} \pm 10\%, V_{DISP} = 8 \text{ to } 18 \text{ V}, f_{CLK} = 5.0 \text{ MHz}, Ta = -40 \text{ to } +105^{\circ}\text{C}, \text{ unless otherwise specified})$

*1 : DATA, CLOCK, LOAD ENABLE terminals.

*2 : OUTPUT1 to 13, OUTPUT22 to 33 terminals.

*3 : OUTPUT14 to 21 terminals.

*4 : To BLANK_BAR input, the low level driver capability more than 600uA should be set.

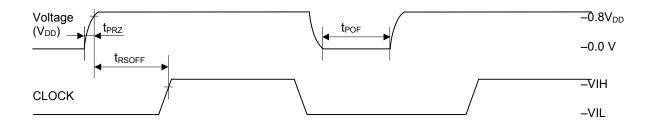
AC Characteristics

$(V_{DD} = 5.0 \text{ V}\pm 10\% \text{ or } 3.3 \text{ V}\pm 10\%, V_{DISP} = 8 \text{ to } 18 \text{ V}, f_{CLK} = 5.0 \text{ MHz}, \text{ Ta} = -40 \text{ to } +105^{\circ}\text{C}$, unless otherwise specific									
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit			
CLOCK Pulse Width	t _w (CLK)	_	100			ns			
DATA Setup Time	t _{su} (D-CLK)	_	50			ns			
DATA Hold Time	t _H (CLK-D)	—	50			ns			
CLOCK - LOAD ENABLE			50						
Setup Time	t _{SU} (CLK-LAT)	—	50			ns			
LOAD ENABLE - CLOCK	t _{s∪} (LAT-CLK)	Normal Operation	50						
Setup Time	ISU(LAT-CLK)	Normal Operation	50			ns			
LOAD ENABLE Pulse Width	t _w (LAT)		400			ns			
BLANK_BAR Pulse Width	t _W (BK)		5	_	_	μS			
DATA OUT Delay Time	t _{PD}	C ₁₁ = 30 pF	_	25	50	ns			
All Output Delay Time	t _{DLH}	C _{ld} = 100 pF	_	1.0	2.0	μS			
	t _{DHL}		_	1.0	2.0	μS			
	tтьн	C _{I d} = 100 pF	_	0.5	1.0	μS			
All Output Slew Rate	t	t _R = 20 to 80%		0.5	1.0				
	t _{THL}	t _F = 80 to 20%		0.5	1.0	μS			
V _{DD} Rise Time	t _{PRZ}	Mounted in a unit	—	-	100	μS			
V _{DD} Off Time	taar	Mounted in a unit,	5.0	_		ms			
	t _{POF}	$V_{\text{DISP}} = 0.0 \text{ V}$	5.0 —			1113			
CLOCK Wait Time	t _{RSOFF}	_	300	—		μS			

$(V_{\text{DD}} = 5.0 \text{ V} \pm 10\% \text{ or } 3.3 \text{ V} \pm 10\%, \text{ V}_{\text{DISP}} = 8 \text{ to } 18 \text{ V}, \text{ } f_{\text{CLK}} = 5.0 \text{ MHz}, \text{ } \text{Ta} = -40 \text{ to } +105^{\circ}\text{C}, \text{ unless otherwise specified})$

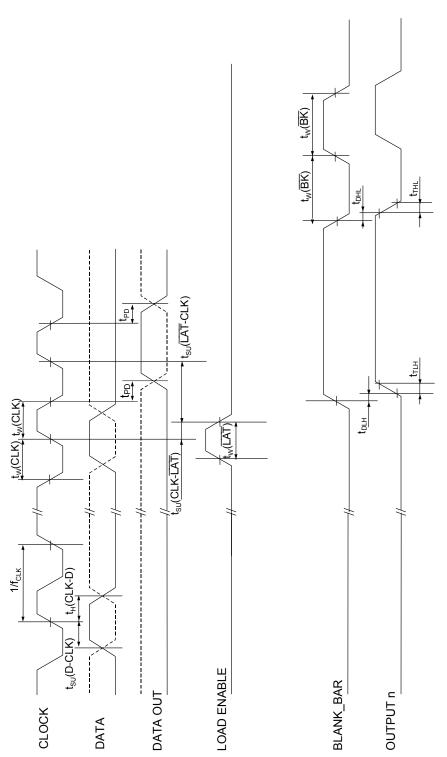
Definition of Input Voltage

Symbol	V_{DD} = 3.3 V ±10%	V_{DD} = 5.0 V ±10%
V _{IH} / V _{IL}	$0.8 V_{DD} / 0.2 V_{DD}$	$0.7 \ V_{DD}$ / $0.3 \ V_{DD}$



TIMING DIAGRAMS

Symbol	V_{DD} = 3.3 V ±10%	V_{DD} = 5.0 V ±10%		
VIH / VIL	$0.8 V_{DD} / 0.2 V_{DD}$	$0.7 V_{DD}$ / $0.3 V_{DD}$		
	$0.8 V_{\text{DISP}} / 0.2 V_{\text{DISP}}$	$0.8 V_{\text{DISP}} / 0.2 V_{\text{DISP}}$		
V _{OH} / V _{OL}	$0.8 V_{DD} / 0.2 V_{DD}$	$0.8 V_{DD} / 0.2 V_{DD}$		



FUNCTIONAL DESCRIPTION

General Description

The ML9270 is a CMOS multi-digit display driver and consists of a 34-bit shift register, a 33-bit latch, and a 33-bit VF tube driver.

Pin Description

(1) DATA

This is a serial data input terminal of the 34-stage shift register.

(2) CLOCK

This is a Clock input terminal of the shift resister to shift an input signal at its leading edge.

(3) LOAD ENABLE

This is an input terminal to transfer the data from the shift register to the data latch circuit to hold it. After the data is held, the terminal initializes the data of the shift register. These functions are executed at the leading edge of an input signal.

(4) BLANK_BAR

This is an input terminal to turn all the OUTPUT terminals OFF(Low), which contains a pull-up resistor.

(5) OUTPUT1 to 33

These are output terminal for the VFD tube driver. Each terminal outputs data which is transferd from the corresponding bit of the shift register and held in the data latch circuit.

(6) DATA OUT

This is a data output terminal of the shift register to output data on the last stage of the 34-stage shift register.

(7) VDD

This is a Logic power supply terminal.

(8) VDISP

This is a driver output power supply terminal.

(9) GND

This is a grounding terminal.

FEDL9270-01

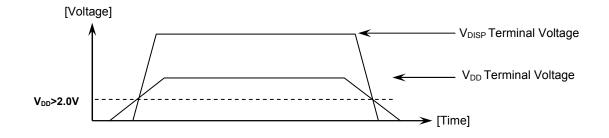
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Register No.	33	32	31	30	29	28	27	26	25	24	23	
OUTPUT No.	33	32	31	30	29	28	27	26	25	24	23	
Register No.	22	21	20	19	18	17	16	15	14	13	12	
OUTPUT No.	22	21	20	19	18	17	16	15	14	13	12	
Register No.	11	10	9	8	7	6	5	4	3	2	1	0
OUTPUT No.	11	10	9	8	7	6	5	4	3	2	1	DATA OUT

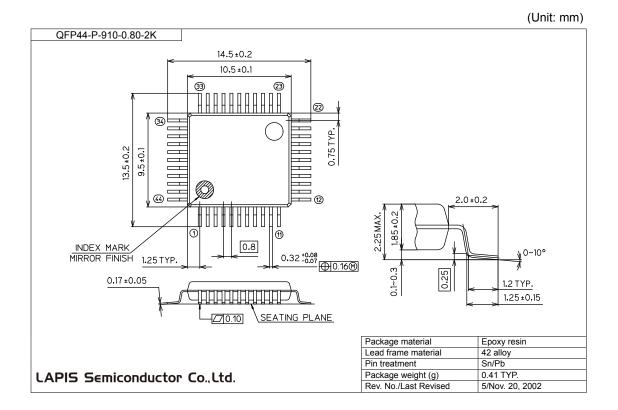
Shift Register Numbers (Bit Numbers) and Corresponding OUTPUT Pin Names (OUTPUT Numbers)(Code 01)

POWER-ON/OFF TIMING



To prevent IC from malfunctioning, after V_{DD} is applied as soon as possible that V_{DISP} is applied. When turning off the power, after V_{DISP} is applied as soon as possible that V_{DD} is applied.

PACKAGE DIMENSIONS



Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact ROHM's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

REVISION HISTORY

		Pa	ge	
Document No.	Date	Previous	Current	Description
		Edition	Edition	
PEDL9270-01	Apr. 14, 2005	-	-	Preliminary edition 1
PEDL9270-02	Jun. 23, 2005	_	_	Block Diagram: Addition of PLA Block Diagram: Addition P.O.R BLANK \rightarrow BLANK Power Dissipation: TBD \rightarrow 266mW Timing Diagram: reversal of BLANK signal $1/\text{fc} \rightarrow \text{f}_{\text{CLK}}$
PEDL9270-03	Jun. 28, 2005	-	_	Block Diagram: Addition of Schmidt to Data AC: Addition of tPRZ,tPOF and tRSOFF AC: Addition of POR Timing DC: Addition of restriction to BLANK Power On/Off Timing: Addition of comment
PEDL9270-04	Jun. 30, 2005	-	-	Pin Configuration: N.C \rightarrow N.C(GND) AC: Deleted of All Output Delay Time Condition
		1, 2, 3, 5, 6 and 7	1, 2, 3, 5, 6 and 7	Changed the pin name from BLANK to BLANK_BAR.
FEDL9270-01	Sep. 1, 2005	-	9	Added two sections.
	COP. 1, 2000	_	11	Added the "PACKAGE DIMENSIONS" Section.
			6	Changed the Load-enable pulse width to 400ns.

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